



SamHop Microelectronics Corp.

**STB28N15**

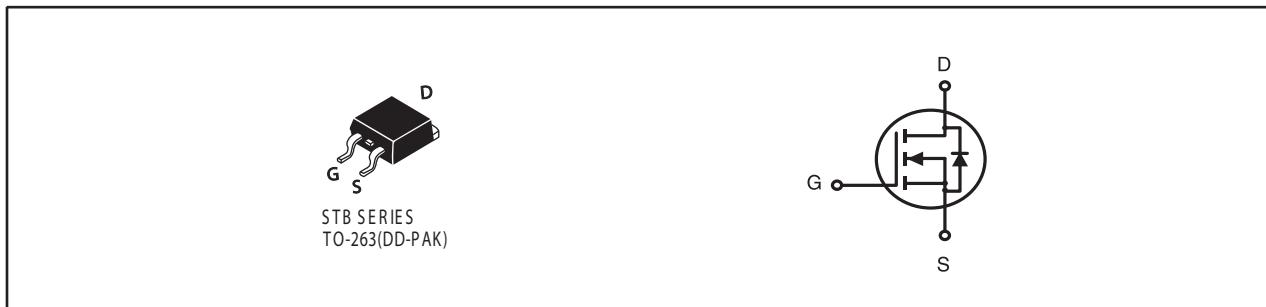
Ver 1.0

N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Max
150V	32A	46 @ VGS=10V
		50 @ VGS=4.5V

FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- TO-263 package.



ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Units
V_{DS}	Drain-Source Voltage	150	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous ^c	32	A
	$T_C=25^\circ\text{C}$	32	A
	$T_C=100^\circ\text{C}$	22.6	A
I_{DM}	-Pulsed ^{a,c}	94	A
E_{AS}	Single Pulse Avalanche Energy ^d	216	mJ
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 175	$^\circ\text{C}$

THERMAL CHARACTERISTICS

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.1	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	55	$^\circ\text{C/W}$

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ELECTRICAL CHARACTERISTICS (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	150			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =120V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V , V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1.2		2.5	V
R _{D(S(ON))}	Drain-Source On-State Resistance	V _{GS} =10V , I _D =20A		35	46	m ohm
		V _{GS} =4.5V , I _D =20A		37	50	m ohm
g _{FS}	Forward Transconductance	V _{DS} =5V , I _D =20A		55		S
DYNAMIC CHARACTERISTICS ^b						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V f=1.0MHz		3760		pF
C _{oss}	Output Capacitance			210		pF
C _{rss}	Reverse Transfer Capacitance			163		pF
SWITCHING CHARACTERISTICS ^b						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =50V I _D =10A V _{GS} =4.5V R _{GEN} = 3.3 ohm		20		ns
t _r	Rise Time			22		ns
t _{D(OFF)}	Turn-Off Delay Time			68		ns
t _f	Fall Time			16		ns
Q _g	Total Gate Charge	V _{DS} =75V, I _D =10A, V _{GS} =4.5V		41		nC
Q _{gs}	Gate-Source Charge	V _{DS} =75V, I _D =10A, V _{GS} =4.5V		11		nC
Q _{gd}	Gate-Drain Charge			22		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _s =1A			1.2	V
Notes						
a.Pulse Test:Pulse Width < 10us, Duty Cycle < 1%.						
b.Guaranteed by design, not subject to production testing.						
c.Drain current limited by maximum junction temperature.						
d.Starting T _J =25°C,L=0.3mH,V _{DD} = 25V.						
e.Mounted on FR4 Board of 1 inch ² , 2oz.						

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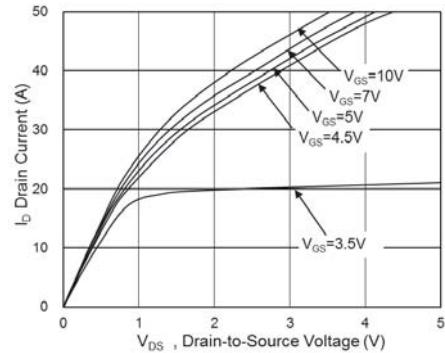


Fig.1 Typical Output Characteristics

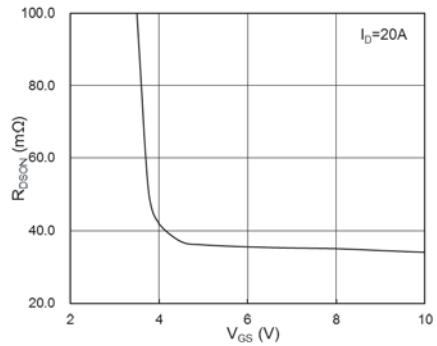


Fig.2 On-Resistance vs. Gate-Source

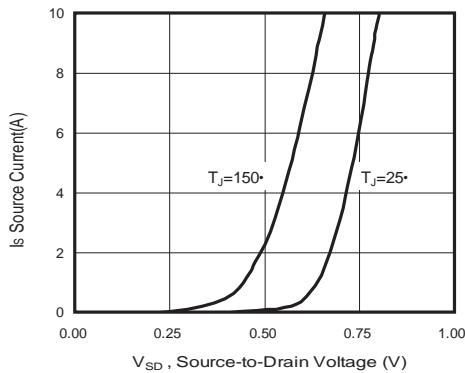


Fig.3 Forward Characteristics Of Reverse

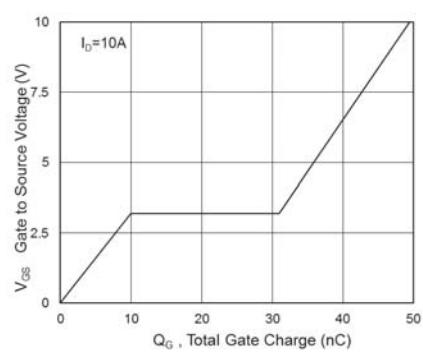


Fig.4 Gate-Charge Characteristics

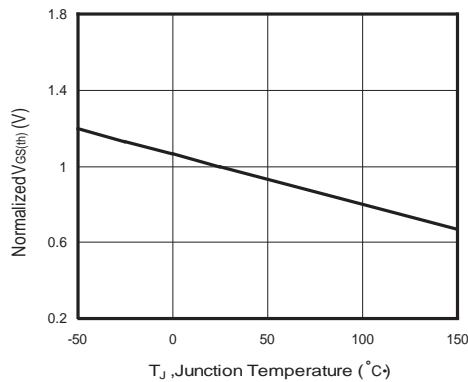


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

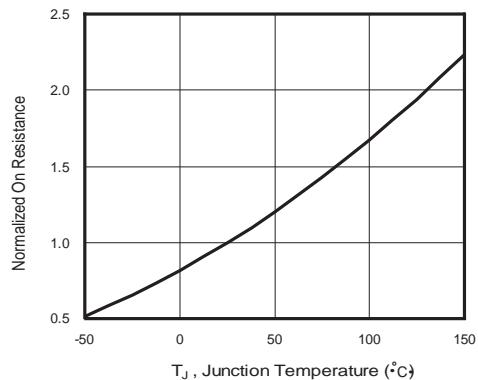


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

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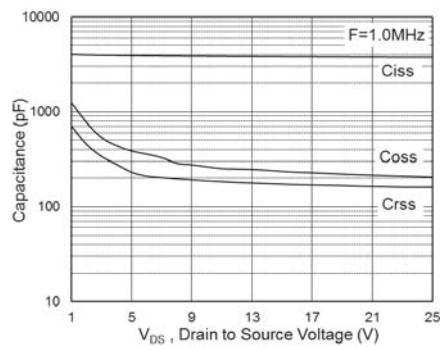


Fig.7 Capacitance

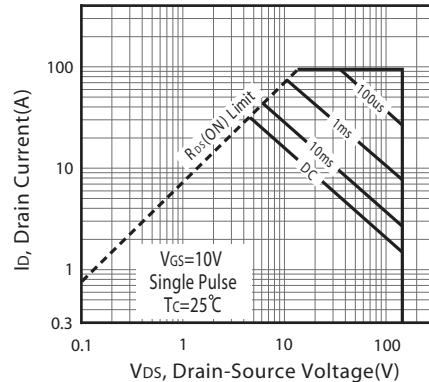


Fig.8 Safe Operating Area

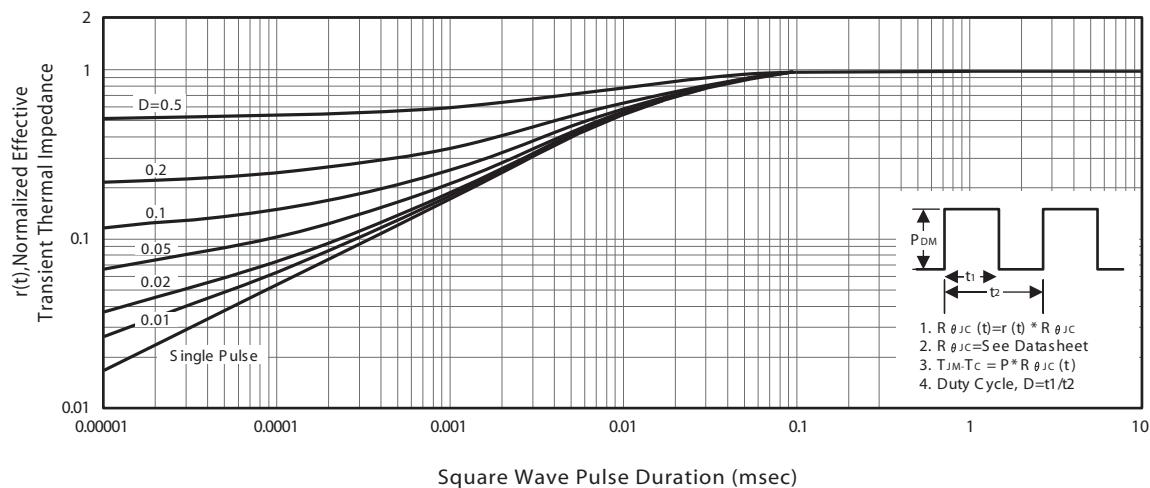
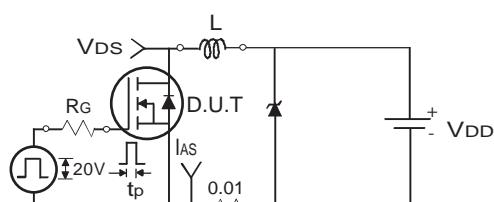
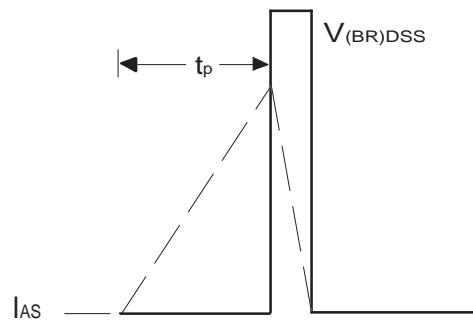


Figure 9. Normalized Thermal Transient Impedance Curve



Uncamped Inductive Test Circuit

Fig.10a



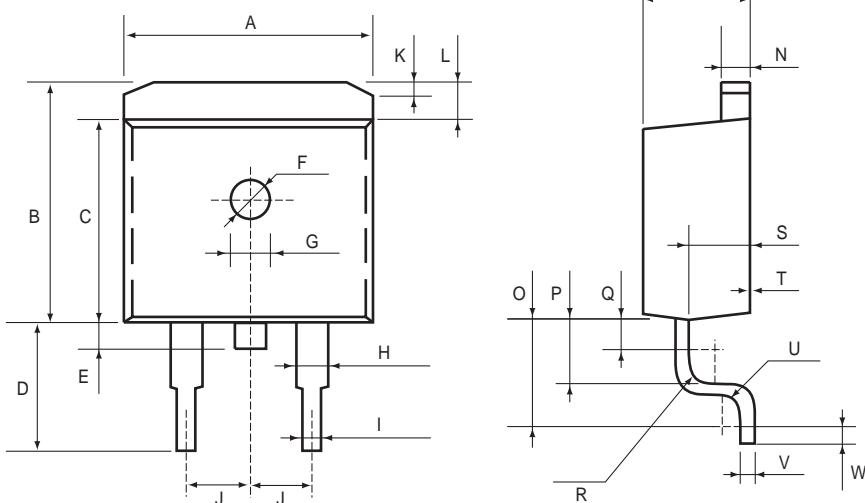
Unclamped Inductive Waveforms

Fig.10b

Apr,08,2016

PACKAGE OUTLINE DIMENSIONS

TO-263AB

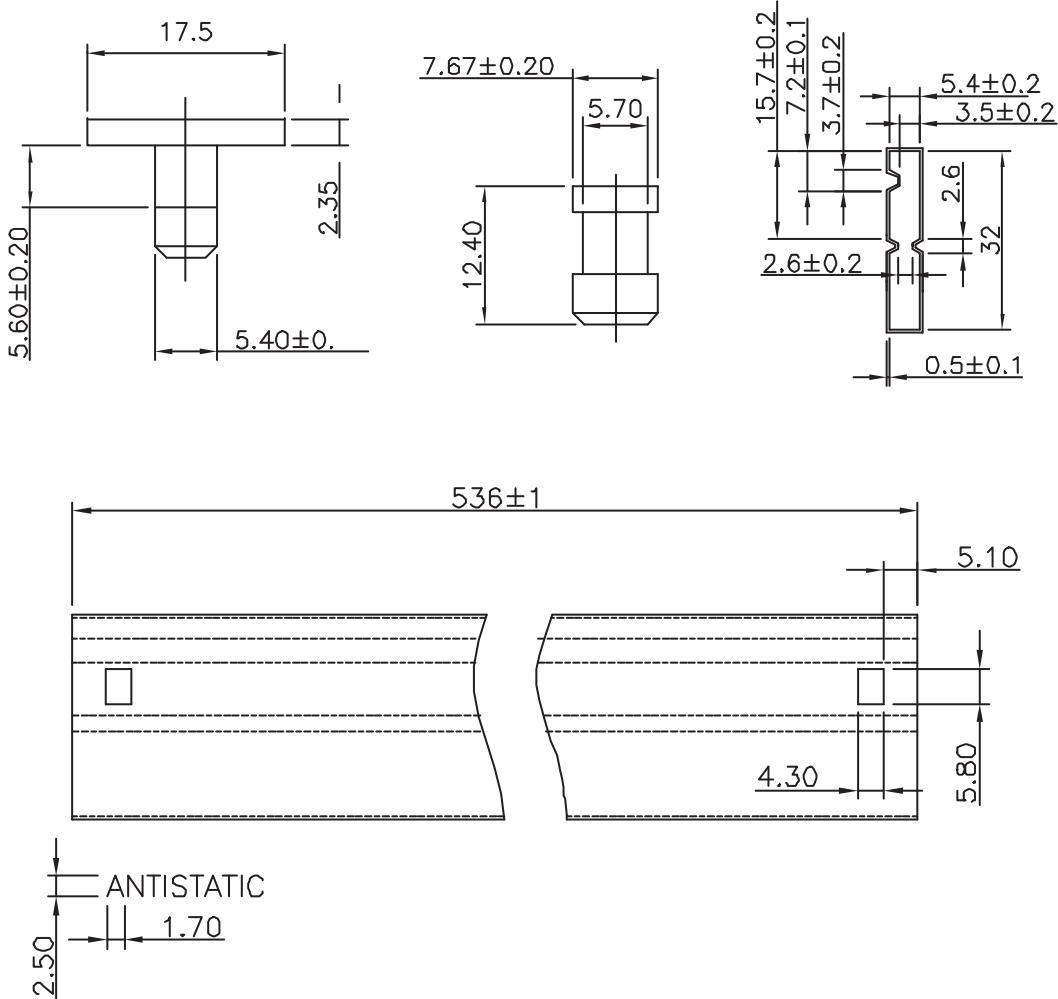


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.9	10.5	0.390	0.413
B	9.5	10.3	0.374	0.406
C	8.3	8.9	0.327	0.350
D	4.7	5.5	0.185	0.217
E	1.5		0.059	
F	ϕ 1.6		ϕ 0.063	
G	1.0	1.4	0.039	0.055
H	1.07	1.47	0.042	0.058
I	0.76	1.06	0.030	0.042
J	2.04	3.04	0.080	0.120
K	0.2	0.6	0.0079	0.024
L	1.4		0.055	
M	4.24	4.64	0.167	0.183
N	1.15	1.45	0.045	0.057
O	3.25	3.75	0.128	0.148
P	2.3		0.091	
Q	1.6		0.063	
R	R0.4	R1.0	R0.0158	R0.0394
S	2.7 MAX		0.106 MAX	
T	0.0	0.3	0.0000	0.0118
U	R0.4	R1.0	R0.0158	R0.0394
V	0.3	0.5	0.0118	0.0197
W	1.2 min		0.047 min	

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TO263AB Tube



TOP MARKING DEFINITION

TO-263

